

(a) forming a plurality of projection electrodes on each of a plurality of semiconductor chips, and applying a thermosetting insulating adhesive to areas of mounting parts where the semiconductor chips are to be mounted on a substrate;

(b) heating said thermosetting insulating adhesive on said substrate with a half-thermosetting temperature so as to retain a degree of viscosity of said thermosetting insulating adhesive, and, concurrently, aligning said semiconductor chips to said mounting parts of the substrate, and performing a first fixing of the semiconductor chips with a first pressure; and

(c) thereafter heating said substrate, on which said semiconductor chips are fixed, with a thermosetting temperature of said thermosetting insulating adhesive, and performing a second fixing of the semiconductor chips with a second pressure, wherein the second pressure for performing the second fixing of the semiconductor chips is greater than the first pressure for performing the first fixing of the semiconductor chips.

REMARKS

Claim 1 has been amended in order to more particularly point out, and distinctly claim the subject matter to which the applicants regard as their invention. The applicants submit that no new matter has been added. It is believed that this Response is fully responsive to the Office Action dated December 4, 1996.